EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER

2002275351

PUBLICATION DATE

25-09-02

APPLICATION DATE

: 19-03-01

APPLICATION NUMBER

: 2001078598

APPLICANT: TORAY IND INC;

INVENTOR: TSUJI YOSHIYUKI;

INT.CL.

C08L 63/00 B29B 9/12 B29C 45/02

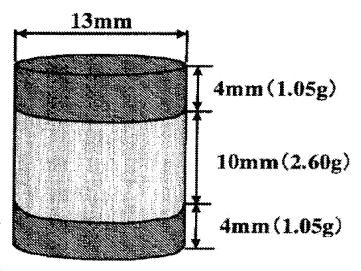
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TITLE

: EPOXY RESIN COMPOSITION TABLET

FOR SEALING SEMICONDUCTOR. AND SEMICONDUCTOR DEVICE MADE BY SEALING WITH THE TABLET



ABSTRACT :

PROBLEM TO BE SOLVED: To provide a group of epoxy resin compositions excellent in

moldability.

SOLUTION: This epoxy resin composition tablet used for sealing a semiconductor, containing an epoxy resin, a curing agent and an inorganic filler is characterized in that it is made from a group of two or more epoxy resin compositions different in the content of a mold release agent, the adhesive power under shear, or the glass transition temperature.

A semiconductor device is obtained by transfer molding using the tablet.

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